

# Bridgelux® SMD 2835 0.2W 3V

Product Data Sheet DS987

### Introduction

SMD 2835



#### Features

- Industry-standard 2835 footprint
- Enables 3- and 6-step MacAdam ellipse custom binning kits
- RoHS compliant and lead free
- Multiple CCT configurations for a wide range of lighting applications

#### Benefits

- Lower operating and manufacturing cost
- Ease of design and rapid go-to-market
- Uniform, consistent white light
- Reliable and constant white point
- Compliant with environmental standards
- Design flexibility

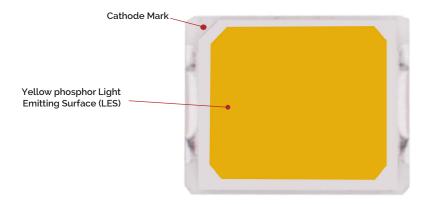


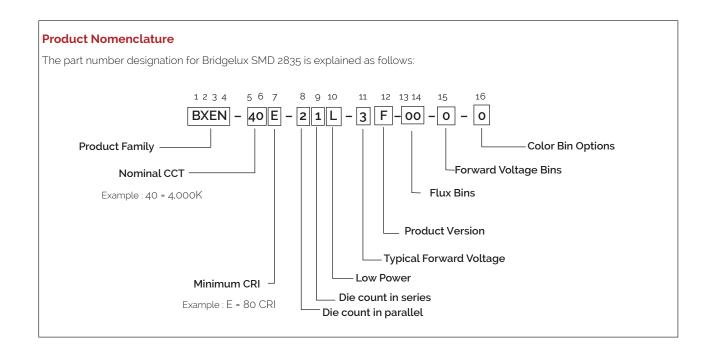
### Contents

Product Nomenclature2Product Selection Guide3Electrical Characteristics4Absolute Maximum Ratings5Product Bin Definitions6Performance Curves9Typical Radiation Pattern12
Electrical Characteristics4Absolute Maximum Ratings5Product Bin Definitions6Performance Curves9
Absolute Maximum Ratings   5     Product Bin Definitions   6     Performance Curves   9
Product Bin Definitions 6   Performance Curves 9
Performance Curves 9
Typical Radiation Pattern 12
Typical Color Spectrum 13
Mechanical Dimensions 14
Reliability 15
Reflow Characteristics16
Packaging 17
Design Resources 19
Precautions 19
Disclaimers 19
About Bridgelux 20

### Product Feature Map

Bridgelux SMD LED products come in industry standard package sizes and follow ANSI binning standards. These LEDs are optimized for cost and performance, helping to ensure highly competitive system lumen per dollar performance while addressing the stringent efficacy and reliability standards required for modern lighting applications.





### Product Selection Guide

The following product configurations are available:

Part Number <sup>1.6</sup>	Nominal CCT <sup>2</sup>	CRI <sup>3, 5</sup>	Nominal Drive Current	F	Forward Voltage <sup>4.5</sup> (V)			Typical Power	Typical Efficacy
	(K)		(mA)	Min	Typical	Max	(lm)4.5	(₩)	(lm/W)
BXEN-27E-21L-3F-00-0-0	2700	80	65	2.60	2.71	2.90	36.0	0.2	204
BXEN-30E-21L-3F-00-0-0	3000	80	65	2.60	2.71	2.90	37.0	0.2	210
BXEN-35E-21L-3F-00-0-0	3500	80	65	2.60	2.71	2.90	37.4	0.2	212
BXEN-40E-21L-3F-00-0-0	4000	80	65	2.60	2.71	2.90	38.7	0.2	220
BXEN-50E-21L-3F-00-0-0	5000	80	65	2.60	2.71	2.90	38.7	0.2	220
BXEN-57E-21L-3F-00-0-0	5700	80	65	2.60	2.71	2.90	38.0	0.2	216
BXEN-65E-21L-3F-00-0-0	6500	80	65	2.60	2.71	2.90	38.0	0.2	216

#### **Table 1:** Selection Guide, Pulsed Measurement Data at 65mA (T<sub>i</sub>=T<sub>sp</sub>=25°C)

#### **Table 2:** Selection Guide, Pulsed Test Performance $(T_{sp} = 85^{\circ}C)^{7.8}$

Part Number <sup>16</sup>	Nomi- nal CCT²	CRI <sup>3.5</sup>	Nominal Drive Current	F	orward Voltage <sup>.</sup> (V)	4.5	Typical Pulsed Flux	Typical Power (W)	Typical Efficacy (lm/W)
	(K)		(mA)	Min	Typical	Max	(lm)4.5		
BXEN-27E-21L-3F-00-0-0	2700	80	65	2.55	2.66	2.85	33.4	0.2	193
BXEN-30E-21L-3F-00-0-0	3000	80	65	2.55	2.66	2.85	34.4	0.2	199
BXEN-35E-21L-3F-00-0-0	3500	80	65	2.55	2.66	2.85	34.7	0.2	201
BXEN-40E-21L-3F-00-0-0	4000	80	65	2.55	2.66	2.85	35.9	0.2	208
BXEN-50E-21L-3F-00-0-0	5000	80	65	2.55	2.66	2.85	35.9	0.2	208
BXEN-57E-21L-3F-00-0-0	5700	80	65	2.55	2.66	2.85	35.3	0.2	204
BXEN-65E-21L-3F-00-0-0	6500	80	65	2.55	2.66	2.85	35.3	0.2	204

Notes for Tables 1 & 2:

1. The last 6 characters (including hyphens '-') refer to flux bins, forward voltage bins, and color bin options, respectively. "00-0-0" denotes the full distribution of flux, forward voltage, and color bin.

Example: BXEN-40E-21L-3F-00-0-0 refers to the full distribution of flux, forward voltage, and color within a 4000K 6-step ANSI standard chromaticity region with a minimum of 80 CRI, 2x1 die configuration, low power, 2,71V typical forward voltage.

- 2. Product CCT is hot targeted at Tsp = 60°C. Nominal CCT as defined by ANSI C78.377-2011.
- 3. Listed CRIs are minimum values and include test tolerance.
- 4. Products tested under pulsed condition (10ms pulse width) at nominal drive current .
- 5. Bridgelux maintains a ±7.5% tolerance on luminous flux measurements, ±0.1V tolerance on forward voltage measurements, and ±2 tolerance on CRI measurements for the SMD 2835.
- 6. Refer to Table 5 and Table 6 for Bridgelux SMD 2835 Luminous Flux Binning and Forward Voltage Binning information.
- 7. Typical pulsed test performance values are provided as reference only and are not a guarantee of performance.
- 8. Typical performance is estimated based on operation under pulsed current with LED emitter mounted onto a heat sink with thermal interface material and the solder point temperature maintained at 85°C. Based on Bridgelux test setup, values may vary depending on the thermal design of the

luminaire and the exposed environment to which the product is subjected.

# **Electrical Characteristics**

#### Table 3: Electrical Characteristics

	Drive Current	Fo	orward Voltag (V) <sup>1,2</sup>	ge	Typical Temperature Coefficient	Typical Thermal Resistance Junction to Solder Point <sup>3</sup> R <sub>j-sp</sub> (°C/W)	
Part Number	(mA)	Minimum	Typical	Maximum	of Forward Voltage ∆V,∕∆T (mV/°C)		
BXEN-XXX-21L-3F-00-0-0	65	2.60	2.71	2.90	-0.85	7.1	

Notes for Table 3:

1. Bridgelux maintains a tolerance of ± 0.1V on forward voltage measurements. Voltage minimum and maximum values at the nominal drive current are guaranteed by 100% test.

2. Products tested under pulsed condition (10ms pulse width) at nominal drive current where Tsp = 25°C.

3. Thermal resistance value was calculated using total electrical input power; optical power was not subtracted from input power.

# Absolute Maximum Ratings

#### Table 4: Maximum Ratings

Parameter	Maximum Rating		
LED Junction Temperature (T <sub>j</sub> )	125°C		
Storage Temperature	-40°C to +105°C		
Operating Solder Point Temperature ( $T_{sp}$ )	-40°C to +105°C		
Soldering Temperature	260°C or lower for a maximum of 10 seconds		
Maximum Drive Current	240mA		
Maximum Peak Pulsed Forward Current <sup>1</sup>	360mA		
Maximum Reverse Voltage <sup>2</sup>	-		
Moisture Sensitivity Rating	MSL 4		
Electrostatic Discharge	2kV HBM. JEDEC-JS-001-HBM and JEDEC-JS-001-2012		

Notes for Table 4:

1. Bridgelux recommends a maximum duty cycle of 10% and pulse width of 10 ms when operating LED SMD at maximum peak pulsed current specified. Maximum peak pulsed current indicate values where LED SMD can be driven without catastrophic failures.

2. Light emitting diodes are not designed to be driven in reverse voltage and will not produce light under this condition. no rating is provided

# **Product Bin Definitions**

Table 5 lists the standard photometric luminous flux bins for Bridgelux SMD 2835 LEDs. Although several bins are listed, product availability in a particular bin varies by production run and by product performance. Not all bins are available in all CCTs.

Bin Code	Minimum	Maximum	Unit	Condition
1G	34	36		
1H	36	38	lm	I <sub>F</sub> =65mA
1J	38	40		I <sub>F</sub> =05IIIA
1K	40	42		

#### Table 5: Luminous flux Bin Definitions at 65mA, T<sub>sp</sub>=25°C

Note for Table 5:

1. Bridgelux maintains a tolerance of  $\pm$  7.5% on luminous flux measurements.

#### **Table 6:** Forward Voltage Bin Definition at 65mA, $T_{sp}$ =25°C

Bin Code	Minimum	Maximum	Unit	Condition
8	2.6	2.7		
9	2.7	2.8	V	I <sub>F</sub> =65mA
A	2.8	2.9		

Note for Table 6:

1. Bridgelux maintains a tolerance of ± 0.1V on forward voltage measurements.

### **Product Bin Definitions**

сст	Color Space	Center Point		Major Axis	Minor Axis	Ellipse	Color Bin
		X	Y			Rotation Angle	
27221/	3 SDCM	0.4578	0.4101	0.0081	0.0042	53.70	1
2700K	6 SDCM	0.4578	0.4101	0.0162	0.0084	53.70	1/A/B/C/D
	3 SDCM	0.4338	0.4030	0.00834	0.00408	53.22	1
3000K	6 SDCM	0.4338	0.4030	0.01668	0.00816	53.22	1/A/B/C/D
a=a a)/	3 SDCM	0.4078	0.3930	0.00834	0.00408	54.00	1
3500K	6 SDCM	0.4078	0.3930	0.01668	0.00816	54.00	1/A/B/C/D
	3 SDCM	0.3818	0.3797	0.00939	0.00402	53.72	1
4000K	6 SDCM	0.3818	0.3797	0.01878	0.00804	53.72	1/A/B/C/D
	3 SDCM	0.3447	0.3553	0.00822	0.00354	59.62	1
5000K	6 SDCM	0.3447	0.3553	0.01644	0.00708	59.62	1/A/B/C/D
	3 SDCM	0.3287	0.3417	0.00746	0.00320	59.09	1
5700K	6 SDCM	0.3287	0.3417	0.01492	0.0064	59.09	1/A/B/C/D
	3 SDCM	0.3123	0.3282	0.00669	0.00285	58.57	1
6500K	6 SDCM	0.3123	0.3282	0.01338	0.0057	58.57	1/A/B/C/D

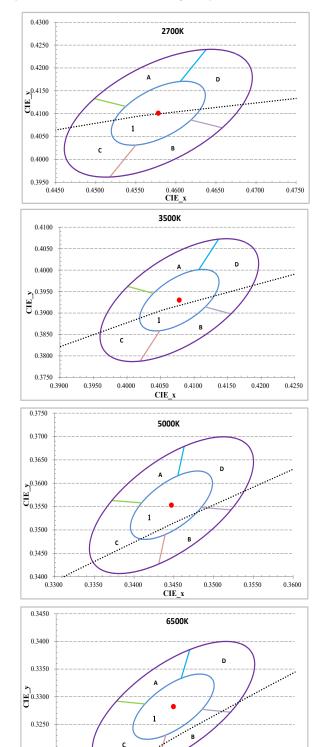
#### Table 7: MacAdam Ellipse Color Bin Definitions

Notes for Table 7:

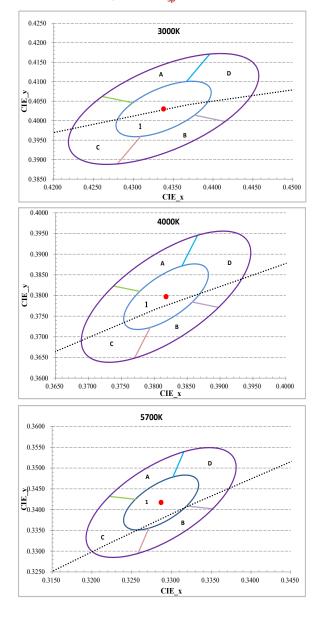
1. Color binning at  $\rm T_{sp}$ =60°C unless otherwise specified.

2. Bridgelux maintains a tolerance of ± 0.007 on x and y color coordinates in the CIE 1931 color space.

### **Product Bin Definitions**







Bridgelux SMD 2835 0.2W 3V Product Data Sheet DS987 Rev. A (05/2023)

<sup>0.3100</sup> CIE x <sup>0.3150</sup>

0.3200

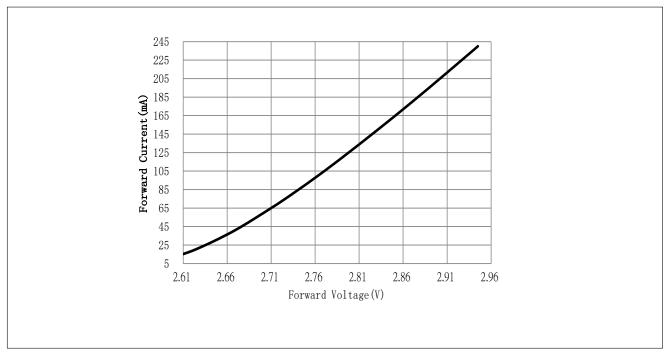
0.3250

0.3050

0.3200

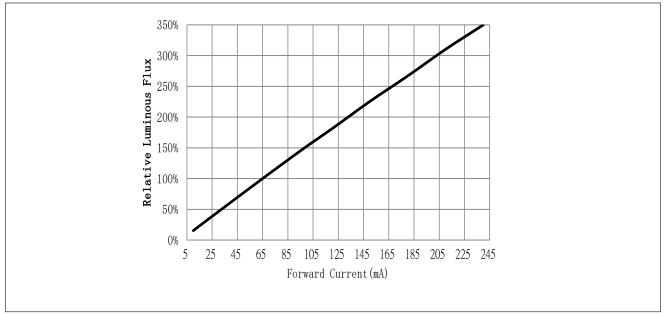
0.3150

### Performance Curves



#### Figure 2: Drive Current vs. Forward Voltage (T<sub>sp</sub>=25°C)

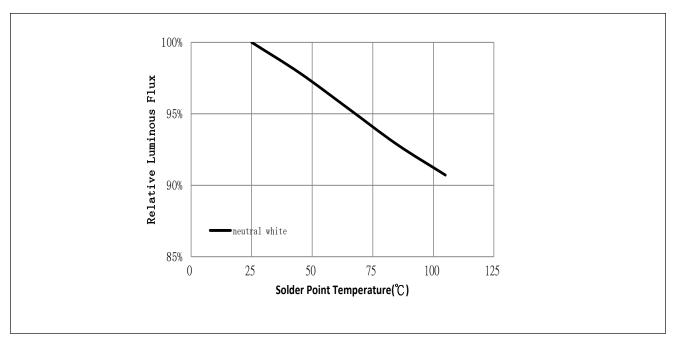
Figure 3: Typical Relative Luminous Flux vs. Forward Current ( $T_{sp}$ =25°C)





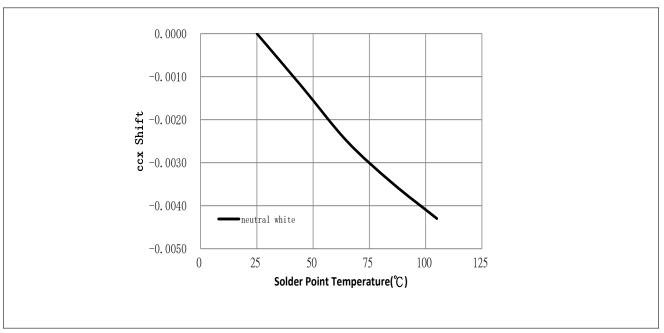
1. Pulse width modulation (PWM) is recommended for dimming effects.

### Performance Curves



#### Figure 4: Typical Relative Flux vs. Solder Point Temperature

Figure 5: Typical ccx Shift vs. Solder Point Temperature

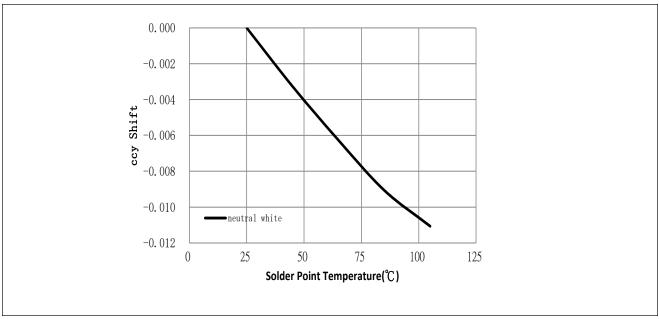


Notes for Figures 4 & 5:

1. Characteristics shown for neutral white based on 4000K and 80 CRI.

2. For other color SKUs, the shift in color will vary. Please contact your Bridgelux Sales Representative for more information.

### Performance Curves



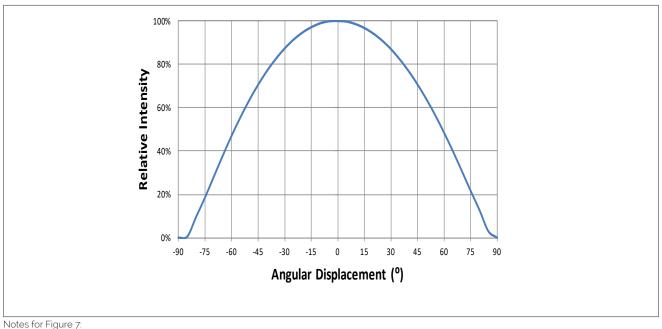
#### Figure 6: Typical ccy Shift vs. Solder Point Temperature

Notes for Figure 6:

1. Characteristics shown for neutral white based on 4000K and 80 CRI.

2. For other color SKUs, the shift in color will vary. Please contact your Bridgelux Sales Representative for more information.

### **Typical Radiation Pattern**

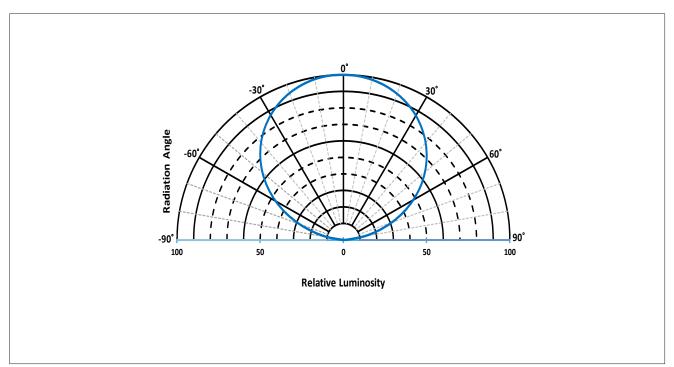


#### Figure 7: Typical Spatial Radiation Pattern at 65mA, $T_{sp}$ =25°C

1. Typical viewing angle is 120°.

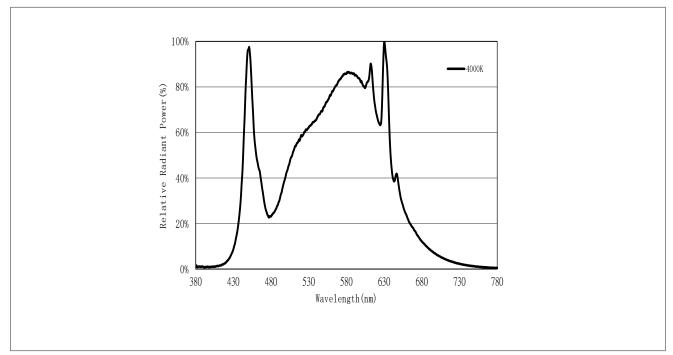
2. The viewing angle is defined as the off axis angle from the centerline where luminous intensity (Iv) is ½ of the peak value.

#### Figure 8: Typical Polar Radiation Pattern at 65mA, T<sub>sp</sub>=25°C



# Typical Color Spectrum

#### Figure 9: Typical Color Spectrum



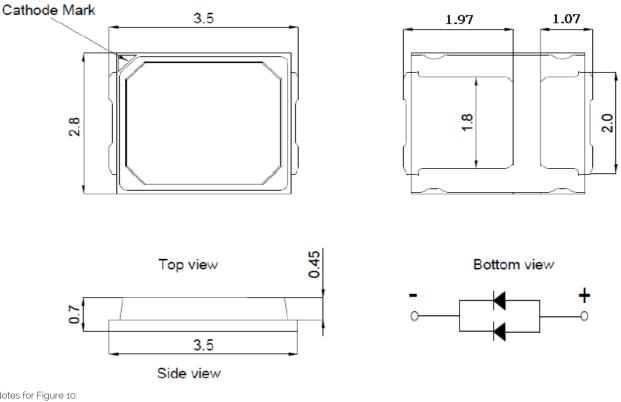
Notes for Figure 9:

1. Color spectra measured at nominal current for Tsp = 25°C

2. Color spectra shown for 80 CRI products.

### **Mechanical Dimensions**

#### Figure 10: Drawing for SMD 2835



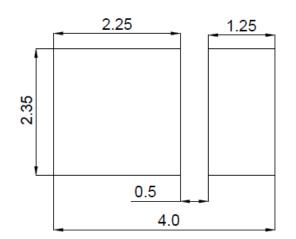
Notes for Figure 10:

1. Drawings are not to scale.

2. Drawing dimensions are in millimeters.

3. Unless otherwise specified, tolerances are ± 0.10mm.

### Recommended PCB Soldering Pad Pattern



# Reliability

#### Table 8: Reliability Test Items and Conditions

No .	Items	Reference Standard	Test Conditions	Drive Current	Test Duration	Units Failed/Tested
1	Moisture/Reflow Sensitivity	J-STD-020E	T <sub>std</sub> = 260°C, 10sec, Precondition: 60°C, 60%RH, 168hr	-	3 reflows	0/20
2	Low Temperature Storage	JESD22-A119	T <sub>a</sub> =-40°C	-	1000 hours	0/20
3	High Temperature Storage	JESD22-A103D	T <sub>a</sub> = 100°C	-	1000 hours	0/20
4	Low Temperature Operating Life	JESD22-A108D	T <sub>a</sub> =-40°C	65mA	1000 hours	0/20
5	Temperature Humidity Operating Life	JESD22-A101C	T <sub>sp</sub> =85°C, RH=85%	65mA	1000 hours	0/20
6	High Temperature Operating Life	JESD22-A108D	T <sub>sp</sub> =105 <sup>°</sup> C	240mA	1000 hours	0/20
7	Power switching	IEC62717:2014	T <sub>sp</sub> = 105°C 30 sec on, 30 sec off	240mA	30000 cycles	0/20
8	Thermal Shock	JESD22-A106B	T <sub>a</sub> =-40°C ~100°C; Dwell : 15min; Transfer: 10sec	-	200 cycles	0/20
9	Temperature Cycle	JESD22-A104E	T <sub>a</sub> =-40°C ~100°C; Dwell at extreme temperature: 15min; Ramp rate < 105°C/min		200 cycles	0/20
10	Electrostatic Discharge	JS-001-2012	HBM, 2KV, 15kΩ, 100pF, Alternately positive or negative	-	-	0/20

#### Passing Criteria

Item	Symbol	Test Condition	Passing Criteria
Forward Voltage	Vf	65mA	ΔVf<10%
Luminous Flux	Fv	65mA	<b>Δ</b> Fv<30%
Chromaticity Coordinates	(x, y)	65mA	∆u'v'<0.007

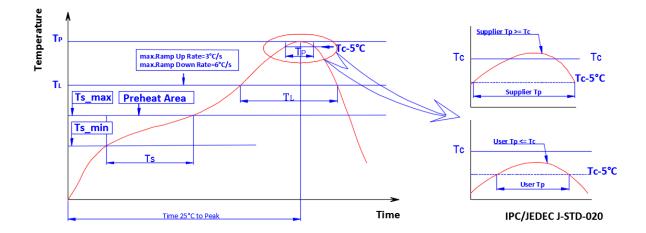
Notes for Table 8:

1. Measurements are performed after allowing the LEDs to return to room temperature

2.  $\mathrm{T_{sld}}$  : reflow soldering temperature;  $\mathrm{T_a}$  : ambient temperature

### **Reflow Characteristics**

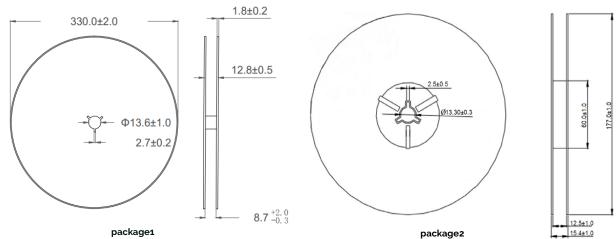
#### Figure 11 : Reflow Profile



Profile Feature	Lead Free Assembly		
Temperature Min. (Ts_min)	160°C		
Temperature Max. (Ts_max)	205°C		
Time (ts) from Ts_min to Ts_max	60-150 seconds		
Ramp-Up Rate (TL to Tp)	3 °C/second		
Liquidus Temperature (TL)	220 °C		
Time (TL) Maintained Above TL	60-150 seconds		
Peak Temp( Tp)	260 °C max.		
Time (Tp) Within 5 $^\circ \rm C$ of the Specified Classification Temperature (Tc)	25 seconds max.		
Ramp-Down Rate (Tp to TL)	5 °C/second max.		
Time 25 °C to Peak Temperature	10 minutes max.		

### Packaging

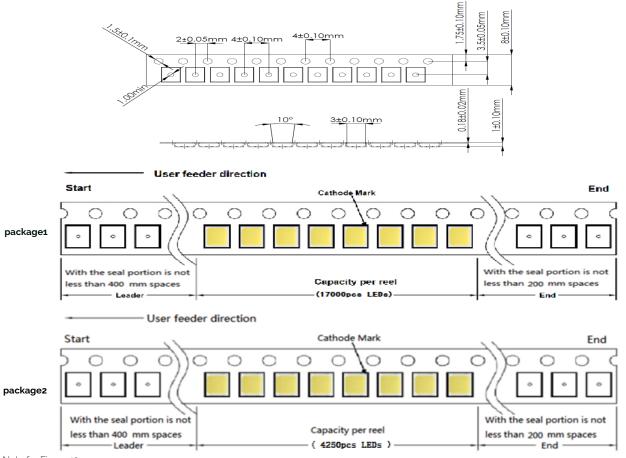
#### Figure 12: Emitter Reel Drawings



Note for Figure 12:

1. Drawings are not to scale. Drawing dimensions are in millimeters.

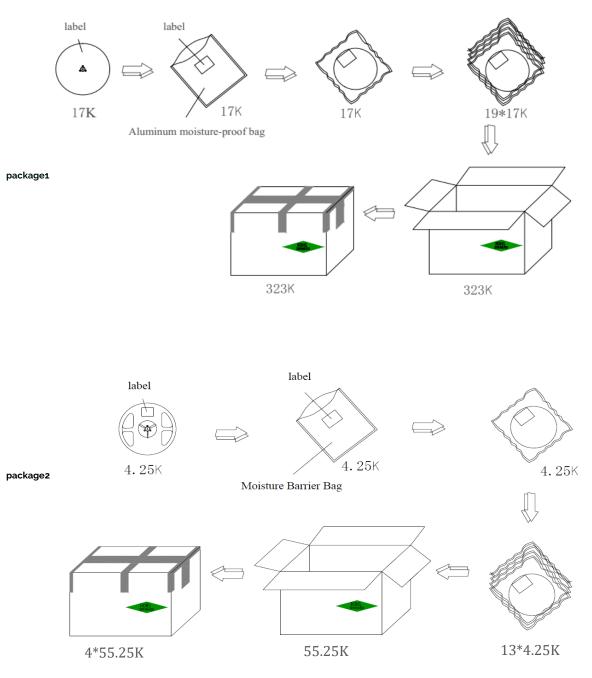
#### Figure 13: Emitter Tape Drawings



Note for Figure 13:

1. Drawings are not to scale. Drawing dimensions are in millimeters.

# Packaging



#### Figure 14: Emitter Reel Packaging Drawings

Note for Figure 14:

1. Drawings are not to scale.

# **Design Resources**

Please contact your Bridgelux sales representative for assistance.

### Precautions

#### CAUTION: CHEMICAL EXPOSURE HAZARD

Exposure to some chemicals commonly used in luminaire manufacturing and assembly can cause damage to the LED emitter. Please consult Bridgelux Application Note AN51 for additional information.

#### CAUTION: EYE SAFETY

Eye safety classification for the use of Bridgelux SMD LED emitter is in accordance with IEC specification EN62471: Photobiological Safety of Lamps and Lamp Systems. SMD LED emitters are classified as Risk Group 1 when operated at or below the maximum drive current. Please use appropriate precautions. It is important that employees working with LEDs are trained to use them safely.

#### CAUTION: RISK OF BURN

Do not touch the SMD LED emitter during operation. Allow the emitter to cool for a sufficient period of time before handling. The SMD LED emitter may reach elevated temperatures such that could burn skin when touched.

### CAUTION

#### CONTACT WITH LIGHT EMITTING SURFACE (LES)

Avoid any contact with the LES. Do not touch the LES of the emitter or apply stress to the LES (yellow phosphor resin area). Contact may cause damage to the emitter

Optics and reflectors must not be mounted in contact with the LES (yellow phosphor resin area).

### **Disclaimers**

#### MINOR PRODUCT CHANGE POLICY

The rigorous qualification testing on products offered by Bridgelux provides performance assurance. Slight cosmetic changes that do not affect form, fit, or function may occur as Bridgelux continues product optimization.

#### STANDARD TEST CONDITIONS

Unless otherwise stated, LED emitter testing is performed at the nominal drive current.

### About Bridgelux: Bridging Light and Life™

At Bridgelux, we help companies, industries and people experience the power and possibility of light. Since 2002, we've designed LED solutions that are high performing, energy efficient, cost effective and easy to integrate. Our focus is on light's impact on human behavior, delivering products that create better environments, experiences and returns—both experiential and financial. And our patented technology drives new platforms for commercial and industrial luminaires.

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